

V _{DSS}	-45V
R _{DS(on)} (Max.)	155mΩ
I _D	-4.5A
P _D	15W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant
- 6) 100% Avalanche tested

Application

Switching Power Supply

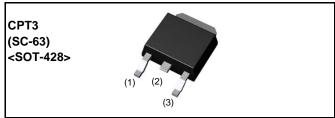
Automotive Motor Drive

Automotive Solenoid Drive

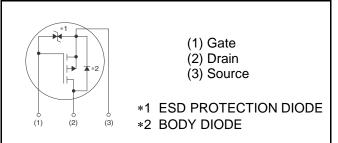
•Absolute maximum ratings(T_a = 25°C)

Value Parameter Symbol Unit V Drain - Source voltage V_{DSS} -45 I_D^{*1} $T_c = 25^{\circ}C$ ±4.5 А Continuous drain current Ι_D^{*1} $T_c = 100^{\circ}C$ ±2.4 А *2 Pulsed drain current ±9.0 А I_{D,pulse} V_{GSS} V Gate - Source voltage ±20 *3 Avalanche energy, single pulse E_{AS} 14.3 mJ *3 Avalanche current -4.5 А I_{AR} $T_c = 25^{\circ}C$ P_{D} 15 W Power dissipation $T_a = 25^{\circ}C$ P_{D} 0.85 W T_i 150 °C Junction temperature $\mathsf{T}_{\mathsf{stg}}$ °C -55 to +150 Range of storage temperature

Outline



Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Tupo	Tape width (mm)	16
Туре	Basic ordering unit (pcs)	2,500
	Taping code	TL
	Marking	046P05

•Thermal resistance

Parameter	Symbol		Values		Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - ambient	R _{thJC}	-	-	8.33	°C/W

•Electrical characteristics($T_a = 25^{\circ}C$)

Deremeter	Symbol	Conditions		Values		Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -1mA$	-45	-	-	V
		$V_{DS} = -45V, V_{GS} = 0V$	_	_	1	
Zoro gato voltago drain current	l	T _j = 25°C	-	-	-1	μA
Zero gate voltage drain current	I _{DSS}	$V_{DS} = -45V, V_{GS} = 0V$			-100	
		T _j = 125°C	-	-		
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μA
Gate threshold voltage	$V_{GS (th)}$	$V_{DS} = -10V, I_{D} = -1mA$	-1	-	-3	V
	R _{DS(on)} *4	$V_{GS} = -10V, I_{D} = -4.5A$	-	110	155	
		$V_{GS} = -4.5V, I_D = -4.5A$	-	160	225	
Static drain - source on - state resistance		$V_{GS} = -4.0V, I_{D} = -4.5A$	-	185	260	mΩ
		$V_{GS} = -10V, I_{D} = -4.5A$		- 180	250	
		T _j = 125°C	-			
Forward transfer admittance	g _{fs}	$V_{DS} = -10V, I_{D} = -4.5A$	3	6	-	S

•Electrical characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	550	-	
Output capacitance	C _{oss}	$V_{DS} = -10V$	-	100	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	50	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq -25V, V_{GS} = -10V$	-	8	-	
Rise time	t _r *4	$I_{\rm D} = -2.0$ A	-	8	-	20
Turn - off delay time	t _{d(off)} *4	R _L = 12Ω	-	35	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	8	-	

•Gate Charge characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol Conditions –		Min.	Тур.	Max.	Onit
Total gate charge	Q_g^{*4}	$V_{DD} \simeq -25V$	-	12	-	
Gate - Source charge	Q_{gs}^{*4}	I _D = -4.5A	-	2.2	-	nC
Gate - Drain charge	Q_{gd} *4	$V_{GS} = -5V$	-	2.2	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq -30V, \ I_D = -4.5A$	-	-3.4	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous source current	ا _S *1	T _c = 25°C	-	6	-4.5	А
Pulsed source current	I_{SM} *2	1 _c = 25 C	-	-	-9	А
Forward voltage	V_{SD} *4	$V_{GS} = 0V, I_{S} = -4.5A$	-	-	-1.2	V
Reverse recovery time	t _{rr} *4	I _S = -4.5A	-	40	-	ns
Reverse recovery charge	Q_{rr}^{*4}	di/dt = -100A/µs	-	60	-	μC

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10 $\mu s,$ Duty cycle \leq 1%

*3 L \simeq 1mH, V_{DD} = -25V, Rg = 10 Ω , starting T_j = 25°C

*4 Pulsed

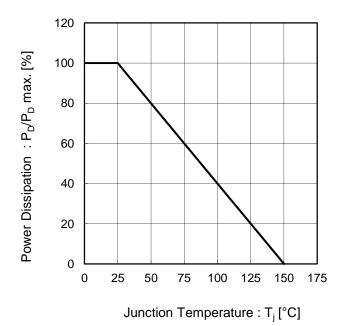
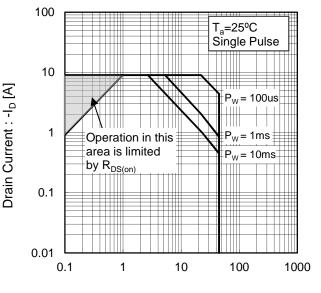


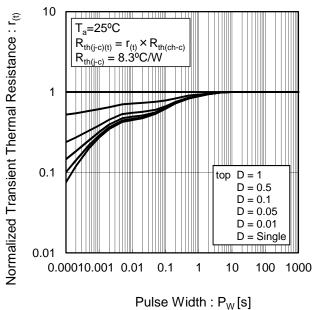
Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : -V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



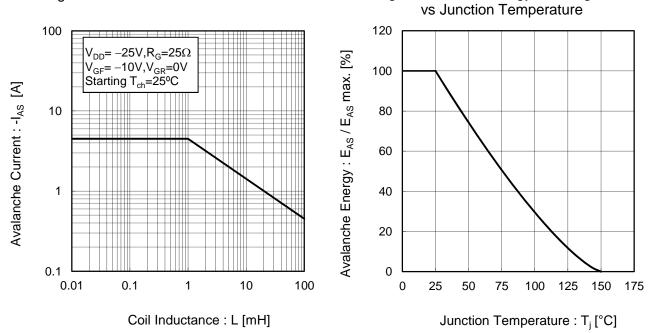


Fig.4 Avalanche Current vs Inductive Load

Fig.6 Typical Output Characteristics(I)

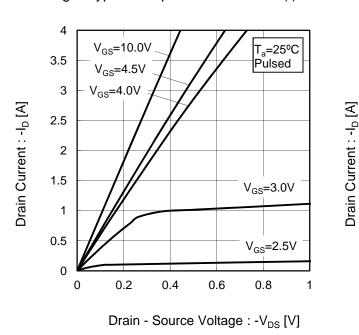
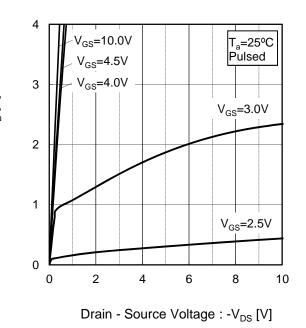
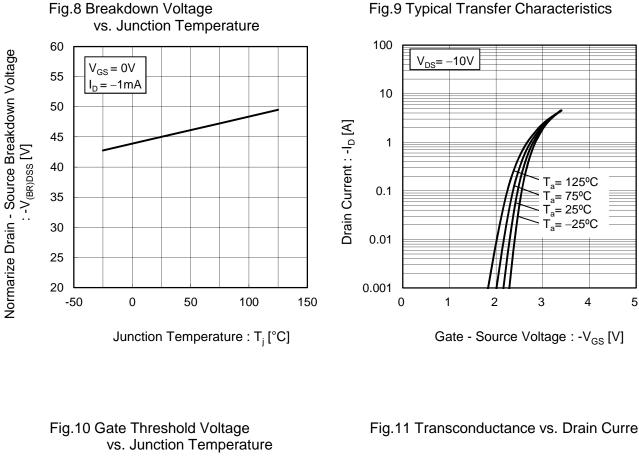


Fig.7 Typical Output Characteristics(II)

Fig.5 Avalanche Energy Derating Curve





3.0 $V_{DS} = -10V$ Gate Threshold Voltage : -V_{GS(th)} [V] $I_D = -1 mA$ 2.5 2.0 1.5 1.0

25

0

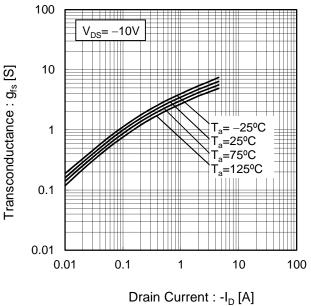
50

Junction Temperature : T_i [°C]

75

100 125 150

Fig.11 Transconductance vs. Drain Current

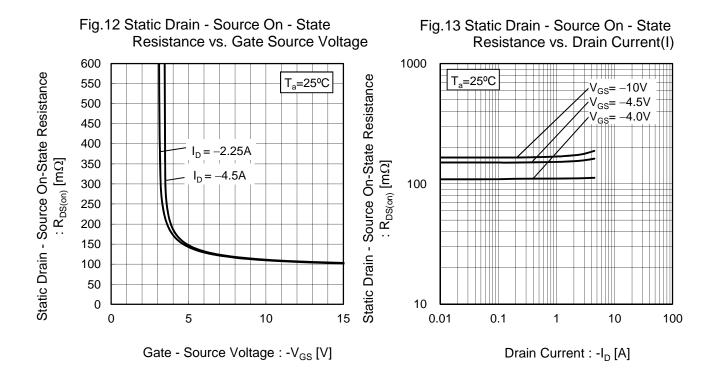


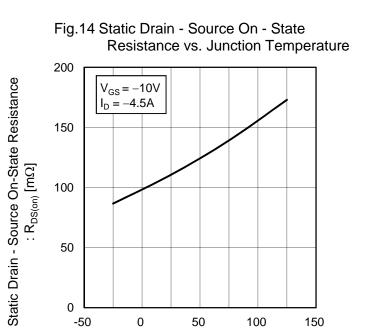
0.5

0.0

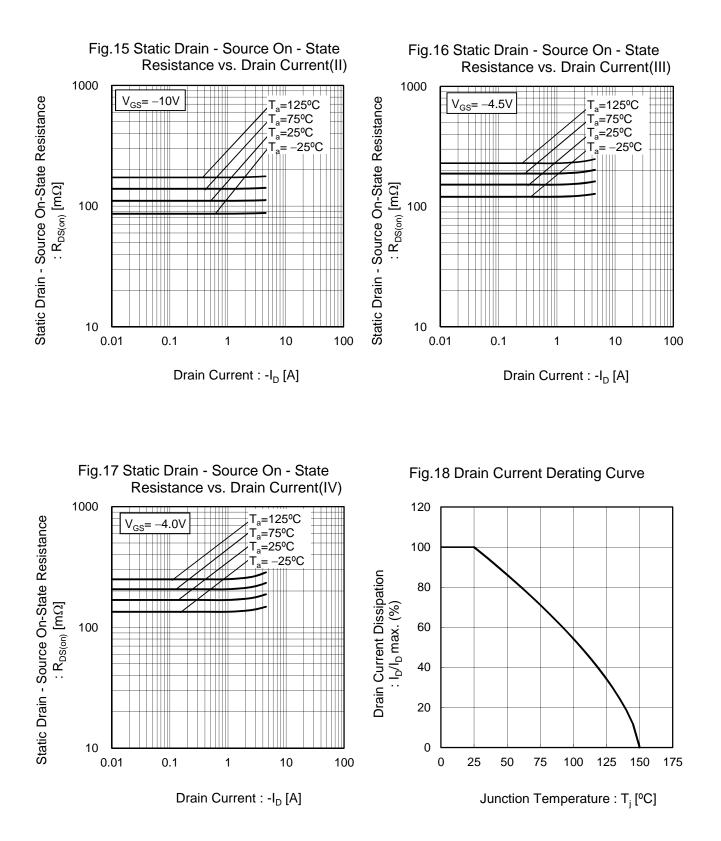
-50

-25





Junction Temperature : T_j [°C]



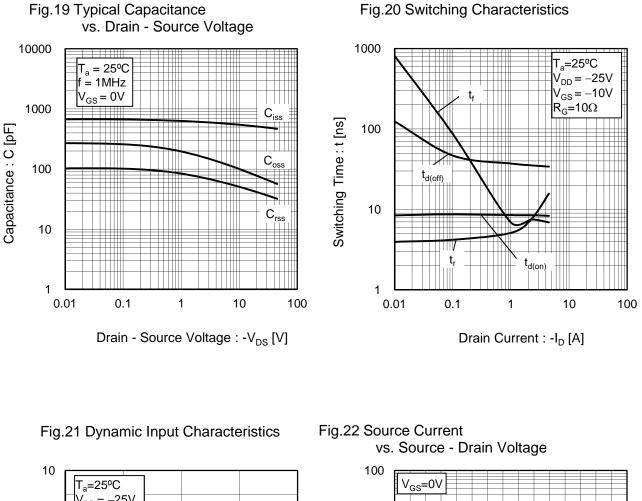
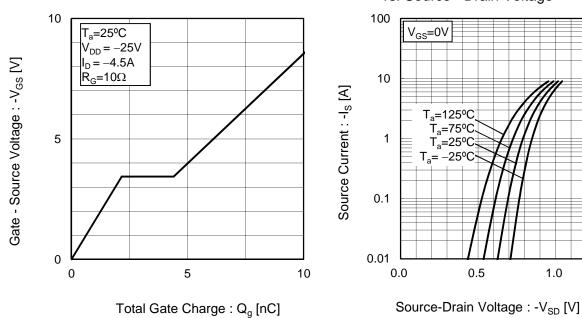
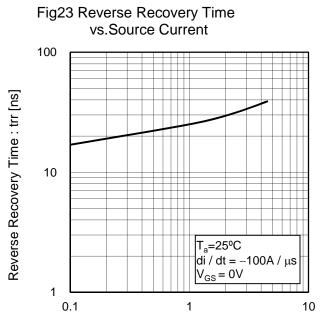


Fig.20 Switching Characteristics



1.0

1.5



Source Current : -I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

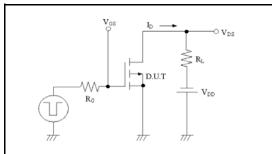


Fig.2-1 Gate Charge Measurement Circuit

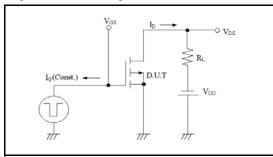


Fig.3-1 Avalanche Measurement Circuit

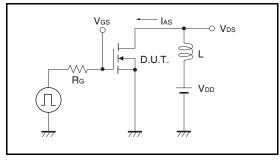


Fig.1-2 Switching Waveforms

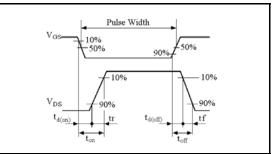


Fig.2-2 Gate Charge Waveform

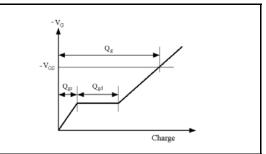
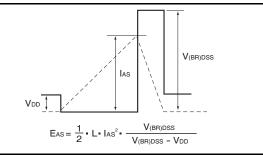
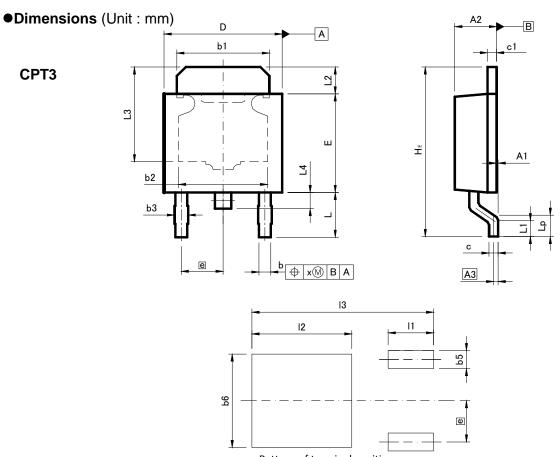


Fig.3-2 Avalanche Waveform





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.15	0.000	0.006
A2	2.20	2.50	0.087	0.098
A3	0.	25	0.0	10
b	0.55	0.75	0.022	0.030
b1	5.00	5.30	0.197	0.209
b2	5.	00	0.1	97
b3	0.	75	0.0	30
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.30	6.70	0.248	0.264
E	5.40	5.80	0.213	0.228
е	2.	30	0.0	91
HE	9.00	10.00	0.354	0.394
L	2.20	2.80	0.087	0.110
L1	0.80	1.40	0.031	0.055
L2	1.20	1.80	0.047	0.071
L3	5.30		5.30 0.209	
L4	0.90		0.0	35
Lp	1.00	1.60	0.039	0.063
х	_	0.25	-	0.010

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
b5	-	1.00	-	0.04
b6	-	5.20	-	0.205
1	-	2.50	-	0.098
12	-	5.50	-	0.217
13	_	10.00	_	0.394

Dimension in mm / inches

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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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 - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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